

About the Company

VSAP LAB is a fully-funded Vietnamese startup specializing in Advanced Packaging solutions for semiconductor chips. We focus on research and innovation to provide design, manufacturing, prototyping, and testing services. Our mission is to deliver the best form factors, performance, and fastest time to market for our customers' chips. We aim to enable a complete semiconductor ecosystem in Vietnam. Through pioneering technology, we accelerate the growth of the local semiconductor industry.

If you are a talented person with a growth mindset, start-up spirit, keen on learning new things everyday and wants to be part of a journey that have a big impact for generations to come, this might be a perfect role for you.

Job Title: RDL (Principal) Process Engineer – Advanced Packaging

- Location: Danang, Vietnam
- Department: Advanced Packaging / Backend Technology
- Employment Type: Full-Time

Position Overview

We are seeking a highly skilled and motivated Redistribution Layer (RDL) (Principal) Process Engineer to join our R&D Advanced Packaging team. This role is pivotal in developing and optimizing RDL processes for next-generation fan-out wafer-level packaging (FOWLP), 2.5D/3D integration, and chiplet-based architectures. The ideal candidate will bring deep expertise in lithography, metallization, and polymer patterning, along with a passion for innovation in heterogeneous integration.

Key Responsibilities

- Work with group leader to develop and optimize RDL process modules including lithography, PVD, ECP, polymer patterning, dry/wet clean and temporary adhesive layers.
- Evaluate and qualify chemical, tools vendor for RDL processes.
- Collaborate cross-functionally with design, integration, and reliability teams to ensure robust process flows for advanced packaging.
- Interface with equipment suppliers to troubleshoot and enhance tool performance.

Requirements

- Master's or Ph.D. in Materials Science, Electrical Engineering, Chemical Engineering, or related field.
- 5+ years of experience in semiconductor process or advanced packaging with a focus on RDL processes.
- Hands-on experience with related RDL processes like lithography, Cu metallization, polymer materials, CMP and dry/wet cleaning.
- Familiarity with metrology techniques such as SEM, AFM, XPS, and TEM.
- Strong analytical skills and proficiency in DOE, and failure analysis.
- Excellent communication and collaboration skills across multidisciplinary teams.
- Experience with cleanroom operations, semiconductor manufacturing industry and facility management is a plus.

Why VSAP LAB

- Work in first advanced packaging Lab, the only RnD lab in VN with full machines capability and cooperative/innovative culture.
- Co-founder teams are Vietnamese from leading global companies in semiconductor industry with rich knowledge and experience
- Have opportunities to collaborate with world-class Lab/engineers in a dynamic and inclusive environment.

Contact

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